IEEE SW Test Workshop
Semiconductor Wafer Test Workshop

Brett Crump
SWTW Program Chair

SWTW 2006 Probe Metrology Panel Overview

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Overview

Last year (SWTW 2006) the workshop hosted a Probe Metrology Panel. The members of the panel were asked to present on a series of questions designed to educate and enlighten the conference audience on the panel member’s probe manufacturing process as it relates to probe cards. The proceedings from SWTW 2006 included all eight metrology panel presentations. But the format and shear volume of data makes it difficult to easily compare a single datum across all eight presentations.

This poster diagrams the collated data from the eight metrology panel presentations. At a glance the viewer can compare any of as many as eighteen different probe production process descriptions for as many as eight semiconductor companies. Some of the companies share the same market segment and some do not.

Panel Members

Freescale
Nadine Aldahhan

Intel
Darren Coil

IBM
Jack Courtney

Micron Technology
Brett Crump

Texas Instruments
Mike Harris

AMD
Jens Kober

Philips
Ger Koch

Qimonda
Frank Pietzschmann

Manufacturing Process Categories

- Wafer Capacity
- Wafer Sizes
- Product Mix
- # of Parts
- Cleanroom Class
- Number of Personnel
- Number of card techs
- Number of Testers
- Tester Types
- Prober Types
- Card Technologies
- Number of Cards
- Card Source
- Do They Ink?
- Card Tracking Process
- Card Cleaning Process
- Card Metrology Used
- Challenges